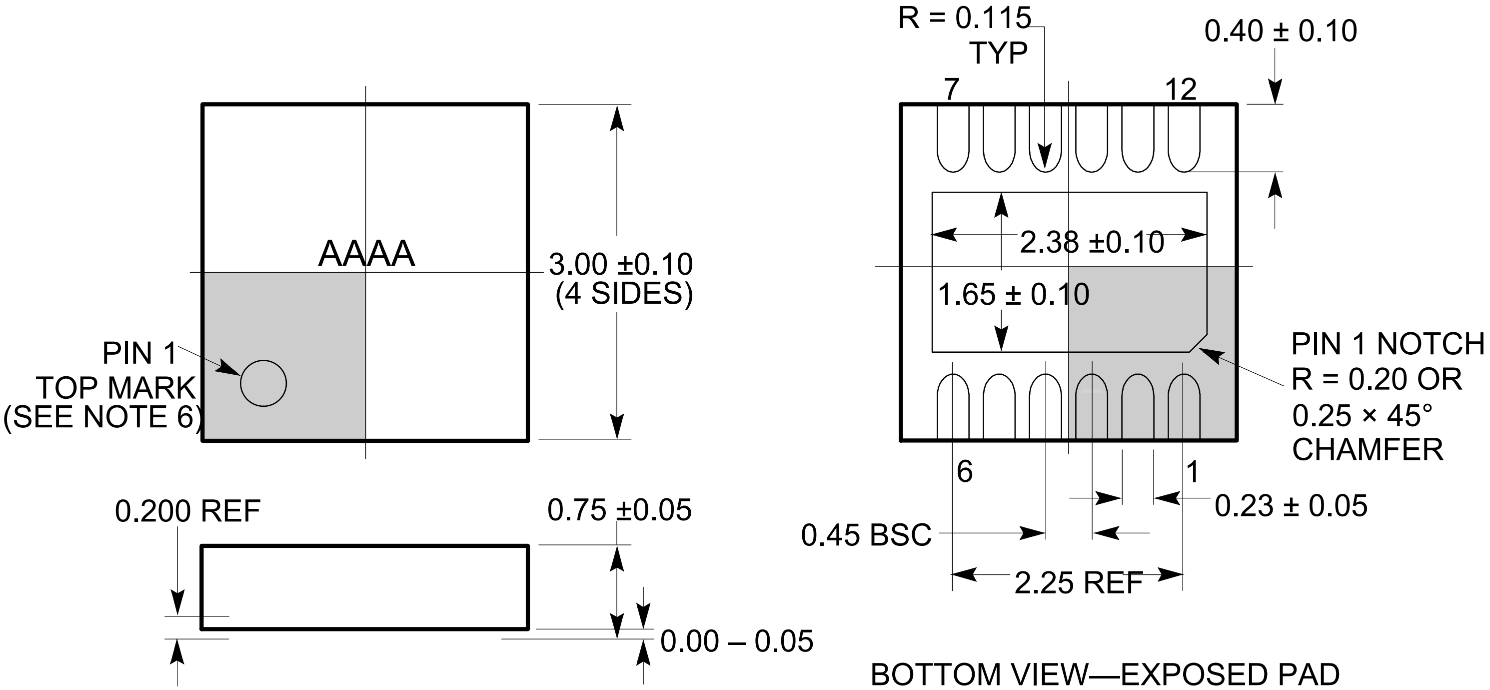
DOCUMENT TYPE:	**POD**
DOCUMENT ID #:	**21-100709**
REVISION:	**A-000**
DOCUMENT TITLE:	**PACKAGE OUTLINE, 12L, TDFN 3x3x0.75 MM**
EFFECTIVE DATE:	**03/06/2023**
EXPIRATION DATE:	
CHANGE NUMBER:	**1180818**
ORIGINATOR:	**Bernard Go**

REASON FOR CHANGE:
INITIAL RELEASE
For ADI LF into MAXIM system.



BOTTOM VIEW—EXPOSED PAD

NOTE:
1. DRAWING IS NOT A JEDEC PACKAGE OUTLINE
2. REFERENCE LTC DWG # 05-08-1725
3. ALL DIMENSIONS ARE IN MILLIMETERS
4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.15mm ON ANY SIDE
5. EXPOSED PAD AND TIE BARS SHALL BE SOLDER PLATED
6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE
7. PACKAGE CODE: T1233+6

ANALOG DEVICES

TITLE: PACKAGE OUTLINE, 12L, TDFN 3x3x0.75 MM			
APPROVAL CHINTANKUMAR PATEL	DOCUMENT CONTROL NO. 21-100709	REV. A	1/1

–DRAWING NOT TO SCALE–

REVISION HISTORY

REV	CHANGES MADE	DATE	INIT.
A	CN 1180818. INITIAL RELEASE For ADI LF into MAXIM system.	03/06/23	BG

TITLE: PACKAGE OUTLINE, 12L, TDFN 3x3x0.75 MM

DOCUMENT I.D.	REVISION	PAGE
21-100709	A	2